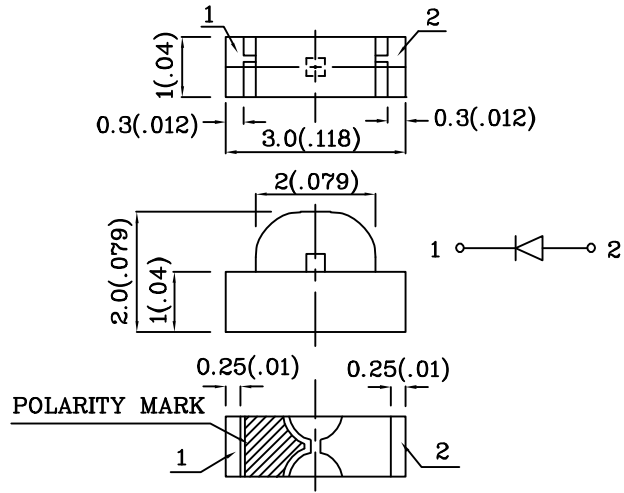


**Features**

- 3.0mmx1.0mm RIGHT ANGLE SMT LED, 2.0mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACK LIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES



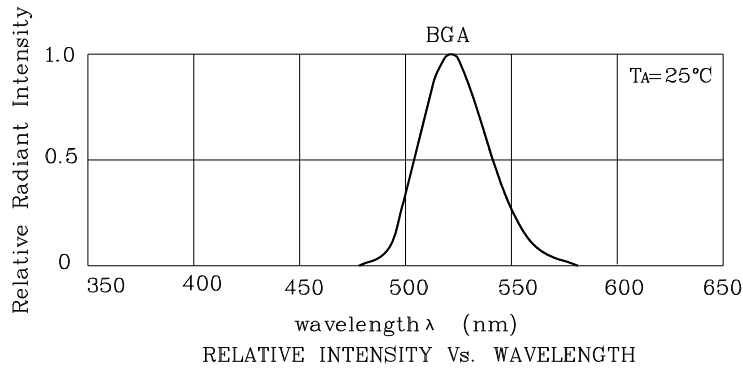
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.15(0.006)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

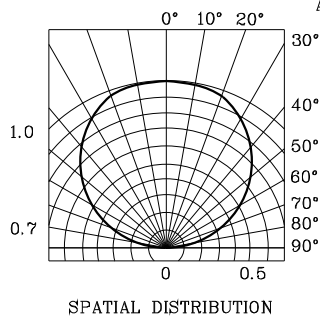
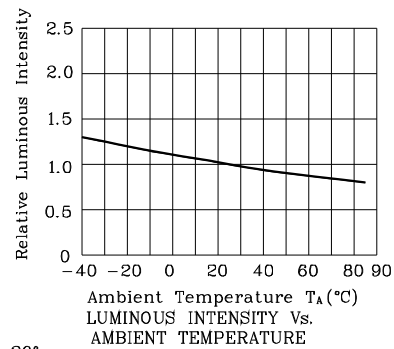
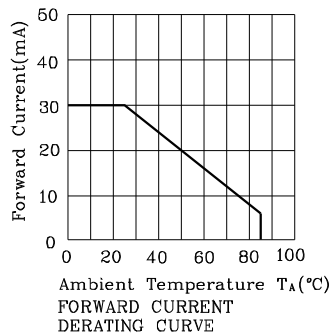
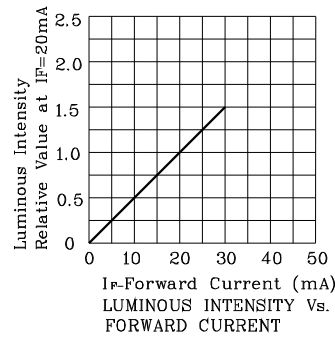
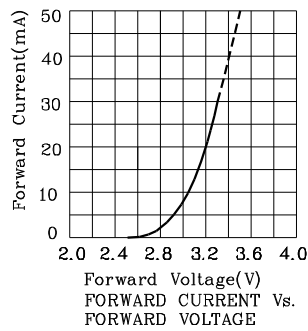
Absolute Maximum Ratings (TA=25°C)		BGA (InGaN)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	100	mA
Power Dissipation	PT	120	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics (TA=25°C)		BGA (InGaN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	3.2	V
Forward Voltage (Max.) (IF=20mA)	VF	4.0	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength Of Peak Emission (Typ.) (IF=20mA)	$\lambda P$	520	nm
Wavelength Of Dominant Emission (Typ.) (IF=20mA)	$\lambda D$	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	35	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	100	pF

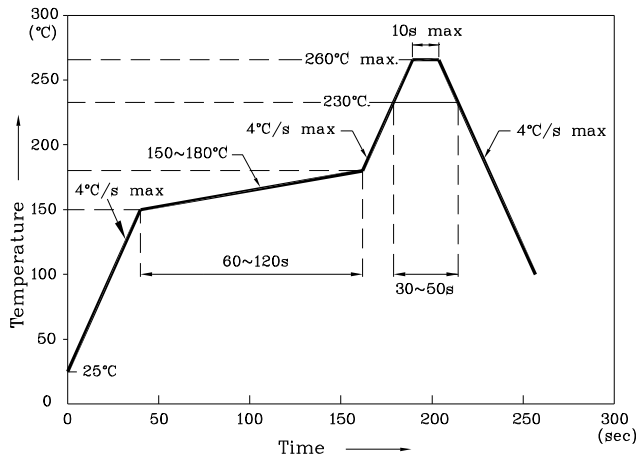
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm $\lambda P$	Viewing Angle 2 $\theta$ 1/2
				min.	typ.		
ZBGA56W	Green	InGaN	Water Clear	70	178	520	120°
Published Date : FEB 25, 2008      Drawing No : SDSA5866      V2      Checked : B.L.LIU      P.1/4							



❖ BGA



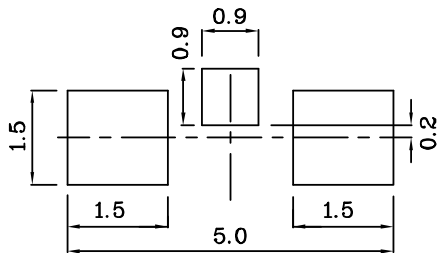
Reflow Soldering Profile For Lead-free SMT Process.



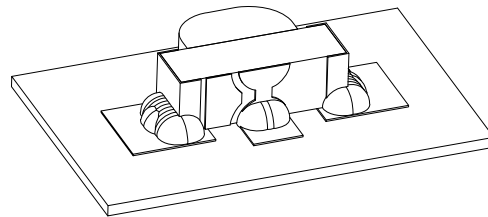
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

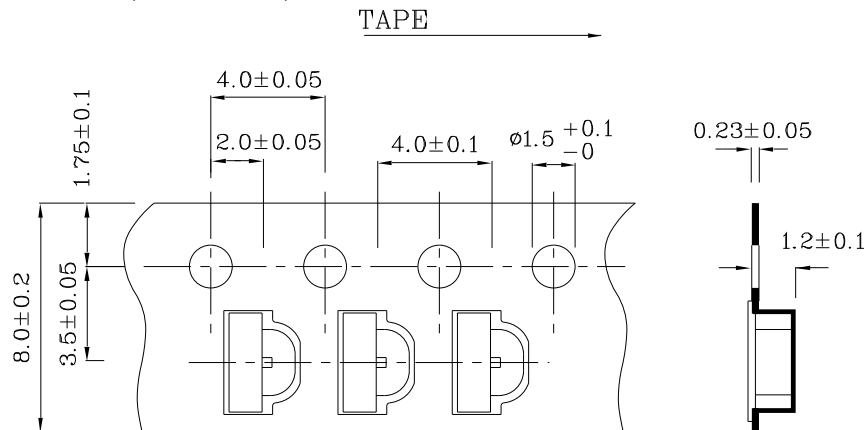
❖ Recommended Soldering Pattern  
(Units : mm; Tolerance: ±0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

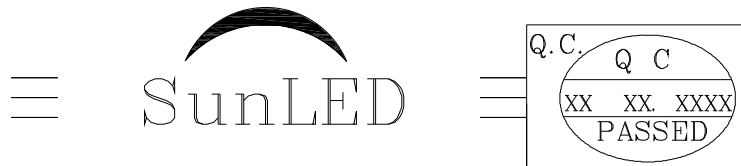
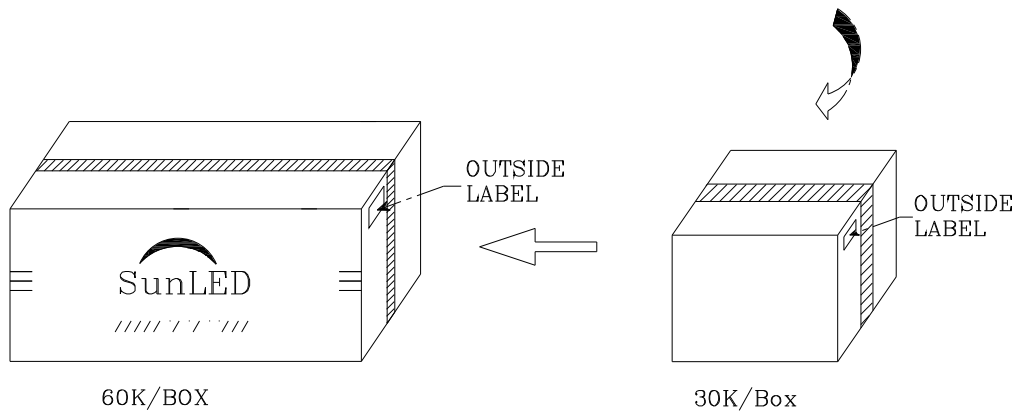
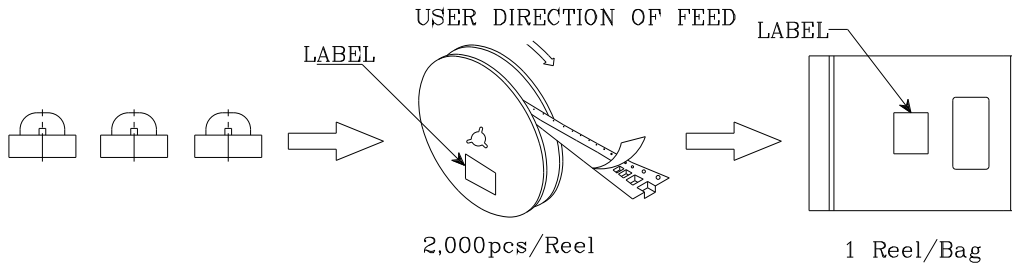
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V


Note: Accuracy may depend on the sorting parameters.



**PACKING & LABEL SPECIFICATIONS**

**ZBGA56W**



P/NO : Zxx56x	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	